

## Advanced Single Wafer Processor

Clean  
Etch  
Strip

For higher throughput and clustered processing, the MultiCap Single Wafer Wet Processing System is featuring multiple process modules arranged either in horizontal or vertical configuration.

Several process modules for cleaning and processing with aqueous or solvent media can be clustered together in multiple process modules.

- **Open spin process modules**  
for aqueous processing
- **Closed spin process modules**  
for solvent processing
- **Single substrate immersion tanks**  
with ultrasonic agitation
- **Spin drying modules**  
with IPA / N<sub>2</sub> atmosphere supported drying modules
- **VUV / Ozone modules**  
for surface conditioning and cleaning
- **Megasonic modules**

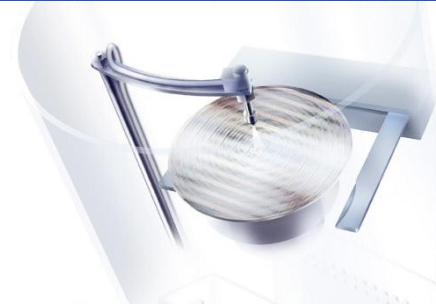
An innovative module for horizontal inline immersion processing of single substrates is available

## Advanced Metal Lift-off Processor

Lift-off

For application requiring clean, residue-free and damage-free device structures, features

- **Solvent Immersion Station**  
for controlled soaking of the wafers in a tempered organic solvent bath with ultrasonic agitation
- **Solvent Spray Station**  
With heated pressurized solvent spray of top side of the wafer and following solvent rinse of top- and backside of wafer
- **Rinse / Spin Dry Station**  
with IPA / and DI-water spray, with megasonics, followed by spin drying
- **Solvent Recirculation Systems**  
with collection system for simple recovery of meal debris and with efficient cascade filtering



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